

**DATE 20 AUG 2007** 

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME
  - Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD **PROTRUSIONS**
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

	MILLIMETERS	
DIM	MIN	MAX
Α	1.35	1.75
A1	0.10	0.25
b	0.35	0.49
С	0.19	0.25
D	9.80	10.00
E	3.80	4.00
е	1.27 BSC	
Н	5.80	6.20
h	0.25	0.50
L	0.40	1.25
M	0°	7°

## **GENERIC MARKING DIAGRAM\***



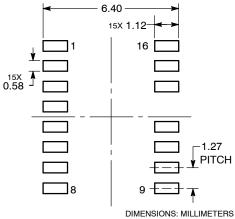
XXXXX = Specific Device Code

= Assembly Location

= Wafer Lot WI Υ = Year WW = Work Week = Pb-Free Package G

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.

## **SOLDERING FOOTPRINT**



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**DESCRIPTION:** SOIC-16 NB, LESS PIN 13 **PAGE 1 OF 1** 

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